A Fresh Look at HPC HUAWEI TECHNOLOGIES

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WORLD CLASS HPC SOLUTIONS TODAY

170+ **Countries** \$74.8B

of Revenue in R&D 2016 Revenue

79,000 **R&D Engineers**

16 **R&D Centers**

36 **Joint Innovation Centers**

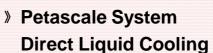
Huawei FusionServer



Modular HPC Systems

14.2%







» Workload Optimization **Ecosystem Partnership**

OceanStor



HPC NVMe Big Data SSD storage storage



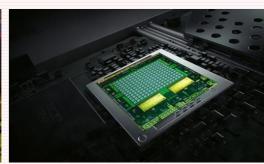
Network Fabric



Modular & Container **Data center**



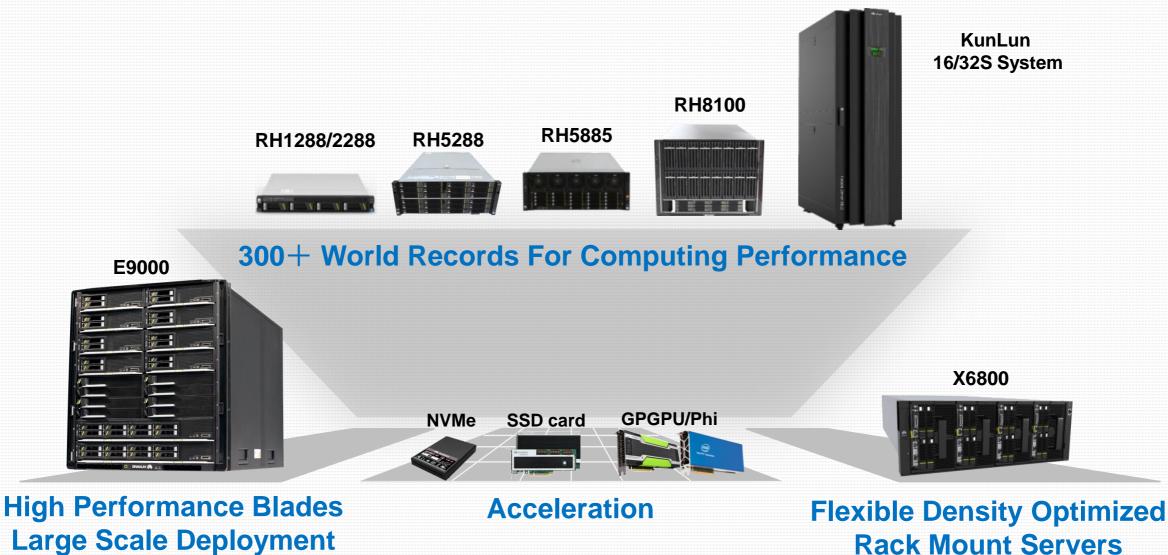
Reduce Complexity More Performance / \$



Design for Growth **HPC Private Cloud**



SERVERS FOR HIGH PERFORMANCE COMPUTING





HUAWEI ADVANTAGES

MAXIMIZE EFFICIENCY



MORE COMPUTE LESS SPACE LOWER POWER CONSUMPTION

- End-to-end energy efficient design
- HVDC
- High Ambient Temperature ~40°C
- Direct Liquid Cooling ~ 84% coverage
- Tight integration with Huawei data center infrastructure

ACCELERATE WORKLOAD



MAXIMIZE PERFORMANCE FOR INDIVIDUAL WORKLOAD

- Flexible, modular architecture
- Multiple innovative form factors
- Deep optimization with hardware acceleration
- Super Fat nodes

ADAPT TO CHANGE



FUTURE PROOF

- Solve problem using emerging hardware technologies
- Single HPC cluster and storage system for both traditional HPC MPI workload and Hadoop
- Leverage flexibility and expandability of cloud technology



END-TO-END GREEN HPC DESIGN

Right-sized Power

~20% better power & cooling utilization

HVDC

Up to 9-15% conversion efficiency improvement

Energy Efficient Server Design

Bottom line of Greener IT



In-Memory Computing

Up to 90+% less power consumption than HDD-based

SSD Storage

Up to 60+% less power consumption than HDD-based

Hardware Acceleration

~ 2X+ Performance Per Watt

Air Containment

Up to 30%↑ in cooling efficiency

Free Air Cooling

Up to 20-70% cooling saving

Higher Temperature

Up to 8%↓ WW DC power consumption w/ 5°C ↑

Hot Water

Eliminate Chiller Free cooling

Green IT Reduces Energy Bill & CO2 Emission, Extends DC Life, Lowers TCO



POWER EFFICIENT FORM FACTORS

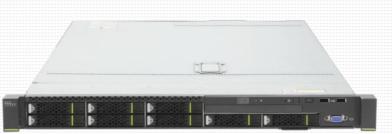
CPU Load	XH620 V3(X6800)	1U Server	Watt Saving Per Node	% Power Saving Per Node
100%	303	313	10	3%
90%	267	283	16	6%
80%	225	235	10	4%
70%	191	206	15	7%
60%	166	183	17	9%
50%	152	164	12	7%
40%	139	151	12	8%
30%	127	138	11	8%
20%	114	125	11	9%
10%	101	112	11	10%
0%	61	73	11.5	16%

X6800



Vs.





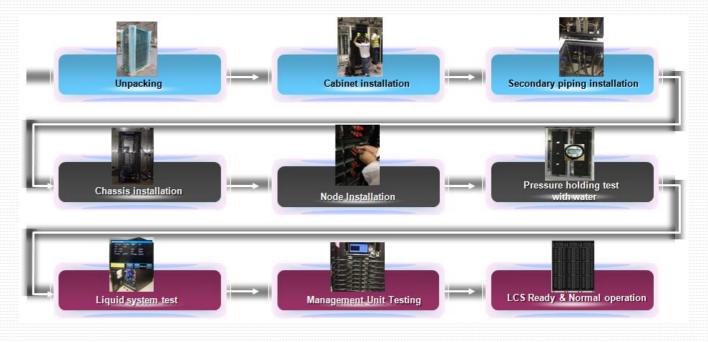
Workload: SPECpower2008, Power Meter: WT210, Thermometer: Digi Watchport/H



HUAWEI FUSIONSERVER LIQUID COOLING SYSTEM



- FusionServer LCS is composed of Liquid Cooling Rack and external CDU
- CPU, Memory and VRD are cooled directly by up to 45 °C water
- Chiller is optional, cooling PUE < 1.1
- Industry leading serviceability



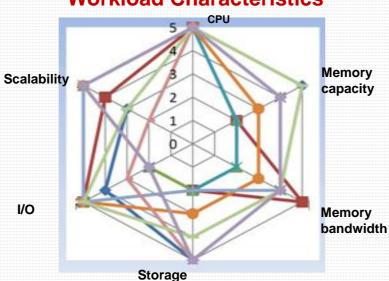


WORKLOAD OPTIMIZED HIGH PERFORMANCE BLADES

Workload Characteristics



Maximize I/O, Hardware Acceleration





Maximize Local Storage Per Node



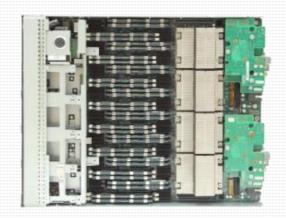
HUAWEI TECHNOLOGIES CO., LTD.



Maximize CPU compute density



Maximize Memory Per Core



Maximize Memory Bandwidth HUAWEI

Chassis

E9000 chassis

Adopts a modular design for computing, storage, switching, power supply, and cooling. 12-U-high chassis, providing 8 full-width or 16 half-width slots.

Supports next 3 generations of high-performance Intel CPUs.

Supports next-decade network technology evolution.

Compute node CH121 V3 CH140 V3 CH225 V3 CH226 V3 CH242 V3 CH220 V3 CH222 V3 Half-width 2*2-socket twin Full-width 4-socket compute node Half-width 2-socket Full-width I/O Full-width storage node Full-width storage node Full-width storage node **Outstanding computing capability** compute nodes compute node All-flash Large memory expansion compute Large memory Super high density (E7 v2. E7 v3) High density node 15*2.5" HDDs/SSDs 12*NVMe SSDs 6*3.5" HDDs **Outstanding computing** Superb storage and I/O expansion Large memory Large memory capability capability capacity 6*PCle slots





X6800 HIGH DENSITY RACK MOUNT SERVERS

High Density Compute Node



Big Data Storage Node



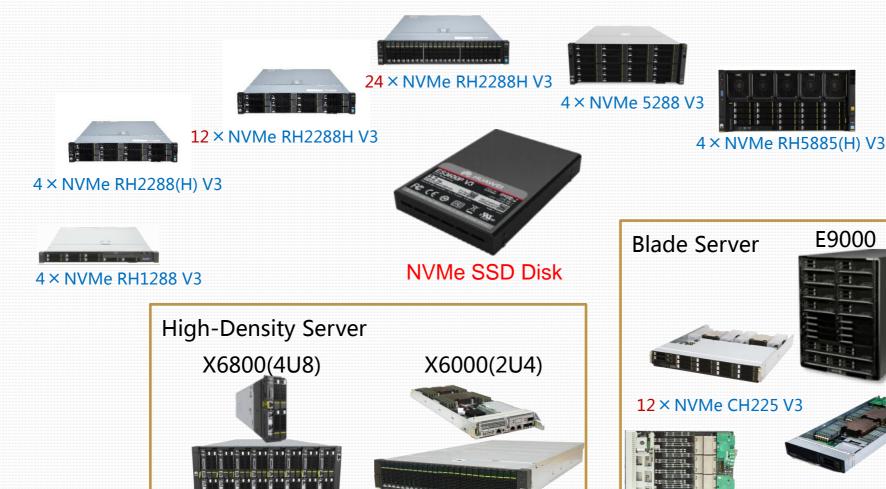


Hardware acceleration Node

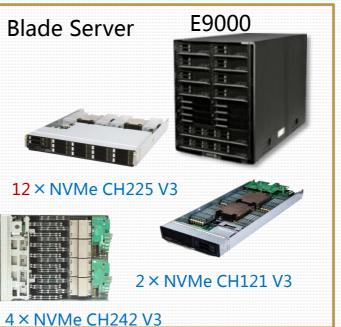




BROAD RANGE OF NVME SSD SERVERS



2 × NVMe XH620 V3

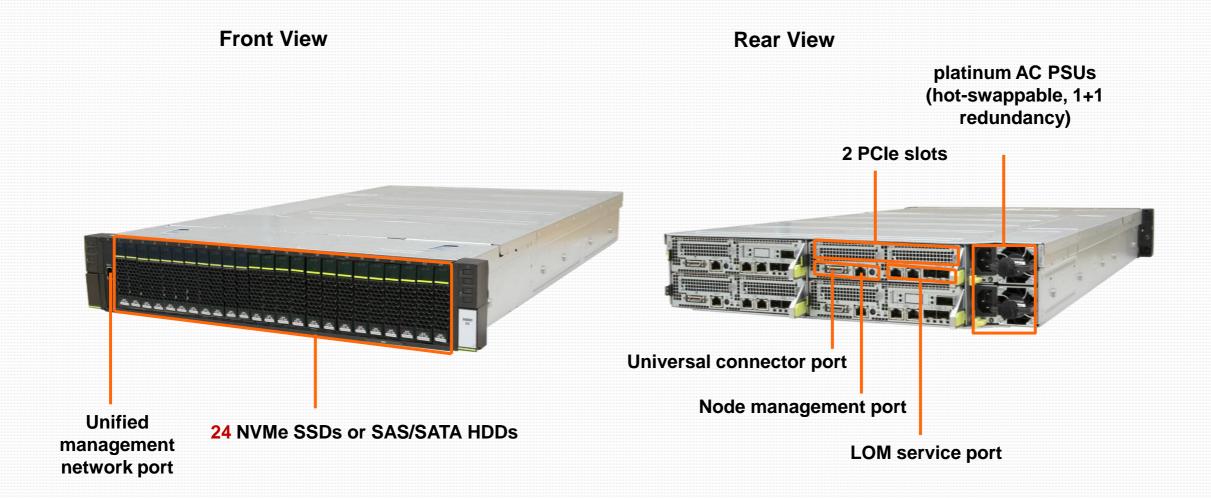




8 × NVMe RH8100 V3

6 × NVMe XH321 V3

FUSIONSERVER X6000 — HIGH-DENSITY SERVER



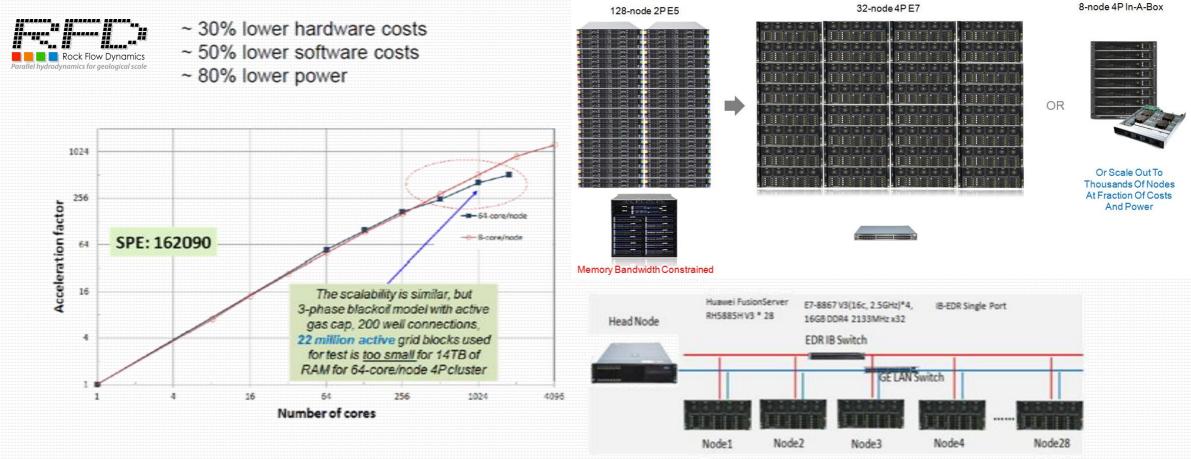


ACCELERATE HIGH MEMORY BANDWIDTH WORKLOAD WITH FAT NODES

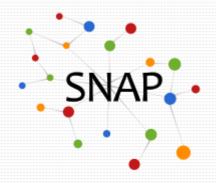
RFD's tNavigator has superior scalability but memory bandwidth constrained

Huawei and RFD collaborated to design and benchmark a new cluster system with Intel E7 4-Socket high memory bandwidth node

Excellent benchmark results



Large Memory Fat Node



SnapVX: http://snap.stanford.edu/snapvx







Huawei FusionServer RH8100 V3

12TB RAM
8 Intel Xeon E7 v3 processors
High RAS capability
High serviceability



HUAWEI OCEANSTOR STORAGE PORTFOLIO

Virtualization, SSD, Distributed Storage, Software Defined Storage

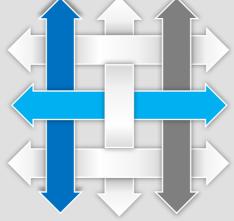
Unified Storage V3 5300, 5500, 5600, 5800, 6800 Block + File

All flash Storage Dorado 2100G2 & 5100 Block

File + Object + Analysis + Archiving

All-in-one Mass Data Storage OceanStor 9000





Full flash storage: best ratio of performance/price





All-in-One storage solution simplifying data lifecycle management

Mass Data Storage UDS

Object for Near line & Offline



For global cloud data centers: **Decentralized & distributed** architecture & highly efficient global data sharing



Unified block & file storage





LEAP FORWARD WITH HUAWEI INNOVATIONS

Enabling HPC Cloud



Big Data Acceleration





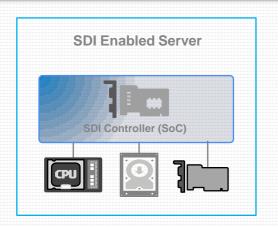
FusionInsight Big Data



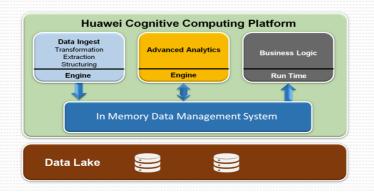
ManageOne Management software >>>>



Software Defined







FusionSphere Cloud OS >>>>





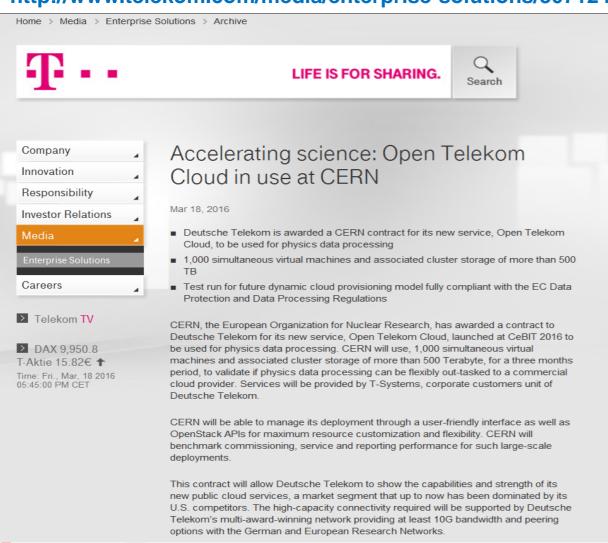
FusionStorage Software Defined Storage Pool $\rangle \rangle \rangle \rangle$



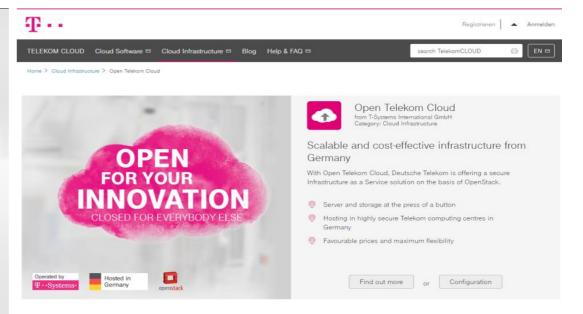


NEWSLETTER ON CERN HPC PROJECT

Accelerating science: Open Telekom Cloud in use at CERN http://www.telekom.com/media/enterprise-solutions/307124



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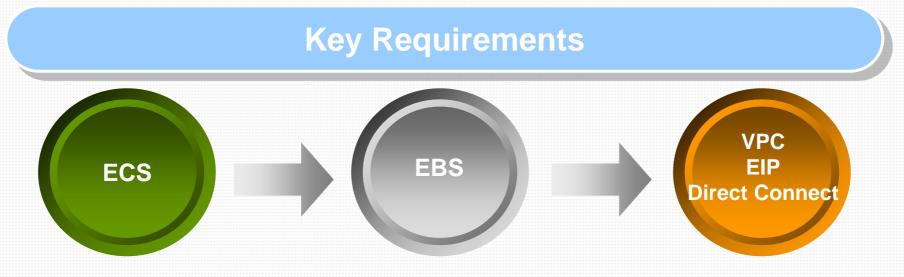


Create your individual laaS solution



Open Telekom Cloud 06.02.2017 1

HPC CLOUD CASE STUDY



HPC resource pool

- 1000VMs (≥ 4vCPU /8GB MEM /100GB local disk)
- No CPU/RAM overcommitment
- KV Performance:
 ≤ 1.2s/event

Low latency block disk

- 500TB block disk
- From VM to block storage roundtrip access RTT≦5ms

High bandwidth network

- Bandwidth from in-house OpenStack data center to VPC on OTC: 10Gbps
- NAT to internet for VMs = 1:1
- 20TB/per day data transmission from in-house OpenStack Cloud to OTC

1000VMs on OTC at the first stage. Potentially 10000 VMs on OTC in the future



HUAWEI HPC MOMENTUM



HUAWEI HPC SOLUTIONS MAXIMIZE ACCELERATE ADAPT

